## DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

APPLICATION DOCKET NO. <u>CS99-343C</u>

As a below named Inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my nam;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled A Method Of Copper/Copper Surface Bonding Using A Conducting Polymer For Application In Ic Chip Bonding

the specification of which (check one)		OIPE
X is attached hereto.	·	
was filed on		OCT 2 1 2002
Application Serial No.		TADEMIN'S
and was amended on (if)  I hereby state that I have reviewed and a		* RADEMAN
I hereby state that I have reviewed and a mended by any amendment referred to		bove Identified specification including the claims, as
I acknowledge the duty to disclose infor Title 37, Code of Federal Regulations, §	rmation which is material to the 1.56(a).	examination of this application in accordance with
I hereby claim foreign priority benefits a inventor's certificate listed below and having a filing date before that of the ap Prior Foreign Application(s)	under Title 35, United States Co ave also identified below any fo plication on which priority is c	ode §119 of any foreign application(s) for patent or preign application for patent or inventor's certificate laimed:
	•	Priority Claimed:
(Number)	(Country)	(Day/Month/Year Filed)
(Number)	(Country)	(Day/Month/Year Filed)
as the subject matter of each of the claim manner provided by the first paragraph of information as defined in Title 37, Code application and the national or PCT inter-09/612,576		ny United States application(s) listed below and, insofatiosed in the prior United States application in the §112, I acknowledge the duty to disclose material a) which occurred between the filing date of the prior lication:
(Application Serial No.)		(patented, pending, abandoned)
I hereby declare that all statements made belief are believed to be true; and further the like so made are punishable by fine o and that such willful false statements may	herein of my own knowledge at that these statements were made imprisonment, or both, under y jeopardize the validity of the	tre true and that all statements made on information and ile with the knowledge that willful false statements and Section 1001 of Title 18 of the United States Code application or any patent issued thereon.
POWER OF ATTORNEY: As a named is application and transact all business in the	inventor, I hereby appoint the fee Patent and Trademark Office	ollowing attorney(s) and/or agent(s) to prosecute this connected therewith. (list name & registration no.)
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